To the Honorable Assistant Secretary and Patent and Trademark Office

1. Name of conveying party(ies): Masahito TANABE; Kazumasa WAKIYA; Masakazu KOBAYASHI; and Toshimasa NAKAYAMA

2. Name and address of receiving party(ies):
   - Name: Tokyo Ohka Kogyo Co., Ltd.
   - Street Address: 150, Nakamaruko, Nakahara-ku
   - City: Kawasaki-shi, Kanagawa-ken Country: Japan

3. Nature of conveyance:
   - Assignment
   - Security Agreement
   - Merger
   - Change of Name
   - Other


4. Application number(s) or patent number(s):
   - A. Patent Application No.(s) 09/173005
   - B. Patent No.(s) Additional numbers attached? No

5. Name and address of party to whom correspondence concerning document should be mailed:
   - Name: WENDEROTH, LIND & PONACK, L.L.P.
     - Attn: Matthew Jacob, Esq.
   - Street Address: 2033 K Street, N.W., Suite 800
   - City: Washington, State: DC ZIP: 20006

6. Total number of applications and patents involved: One

7. Total fee (37 C.F.R. § 3.41) . . . . . $400.00
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   - Authorized to be charged to deposit account

8. Deposit account number: 

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   Matthew Jacob, Reg. No. 25,154
   Name of Person Signing

   October 15, 1998
   Signature
   Date

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   Box Assignments
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ASSIGNMENT

In consideration of the sum of One Dollar ($1.00) and other good and valuable consideration paid to each of the undersigned

Masahito TANABE, Kazumasa WAKIYA, Masakazu KOBAYASHI and

Toshimasa NAKAYAMA

the undersigned hereby sell(s) and assign(s) to

TOKYO OHKA KOGYO CO., LTD.

of 150, Nakamaruko, Nakahara-ku, Kawasaki-shi, Kanagawa-ken, Japan

(hereinafter designated as the Assignee) the entire right, title and interest for the United States as defined in 35 USC 100, in the invention known as

PHOTORESIST STRIPPING LIQUID COMPOSITIONS AND A METHOD OF STRIPPING

PHOTORESISTS USING THE SAME

for which an application for patent in the United States has been executed by the undersigned on even date of the application.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.
The undersigned hereby grant(s) the firm of WENDEROTH, LIND & PONACK, L.L.P., 2033 K Street, N.W., Suite 800, Washington, DC 20006, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date Sep 14, 1998, Name of Inventor Masahito Tanabe
(Masahito
TANABE)
(Kazumasa
WAKIYA)
(Masakazu
KOBAHYASHI)
(Toshimasa
NAKAYAMA)

Date Sep 14, 1998, Name of Inventor Kazumasa Wakiya

Date Sep 14, 1998, Name of Inventor Masakazu Kobayashi

Date Sep 25, 1998, Name of Inventor Toshimasa Nakayama

Date __________________, Name of Inventor ____________________________

Date __________________, Name of Inventor ____________________________

(This assignment should preferably be acknowledged before a United States Consul. If not, then the execution by the Inventor(s) should be witnessed by at least two witnesses who sign here.)

Witness Yasumitsu Taira

Witness Masato Morishita

ACKNOWLEDGEMENT

This __________________ day of __________________________, 19____, before me personally came the above-named ____________________________

________________________________________________________

________________________________________________________

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________________________________________________________

to me personally known as the individual(s) who executed the foregoing assignment, who did acknowledge to me that he (they) executed the same of his (their) own free will for the purposes therein set forth.

________________________________________________________

Official Signature

________________________________________________________

Official Title

The above application may be more particularly identified as follows:

U.S. Application Serial No. ____________________________ Filing Date ____________________________

Applicant Reference Number ____________________________ Atty Docket No. ____________________________

Title of Invention ____________________________